

Serial Interface	Serial 0, 1: 7-, 8-bit × 2 (clock synchronous mode, start-stop synchronous mode, I ² C mode) Serial 2: 7-, 8-bit × 1 (start-stop synchronous mode) Serial 3 to 7: 7-, 8-bit × 5 (clock synchronous mode) Clock source (clock synchronous mode, start-stop synchronous mode) IOCLK; underflow of timer counter; external clock (I ² C mode) IOCLK; underflow of timer counter
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I/O Pins	I/O	155	• Common use : 137
	Input	16	• Common use : 16

A/D Inputs	10-bit × 16-ch.
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PWM	12-, 14-bit resolution × 4-ch. (dedicated), 16-bit resolution × 2-ch. (common with timer)
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ICR	28-bit × 13-ch. + 16-bit × 4-ch. (common with timer)
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OCR	16-bit × 4-ch. (common with timer)
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Timer Synchronous Output	4-bit (synchronous output) × 2-ch.
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Electrical Characteristics

Supply current

Parameter	Symbol	Condition	Limit			Unit
			min	typ	max	
Operating supply current	IDD1	VDDH, VDDB, VDD, PVDD, AVDD = 3.0 V VI = VDDH (VDDB) or VSS At internal = 40 MHz Output open			150	mA
Supply current at stopping	IDD4	VDDH, VDDB, VDD, PVDD, AVDD = 3.6 V VI = VDDH (VDDB) or VSS fosc = oscillation stopped Output open			150*	μA

(Ta = -20°C to +85°C)
*FLGA239-C-1313

A/D conversion performance

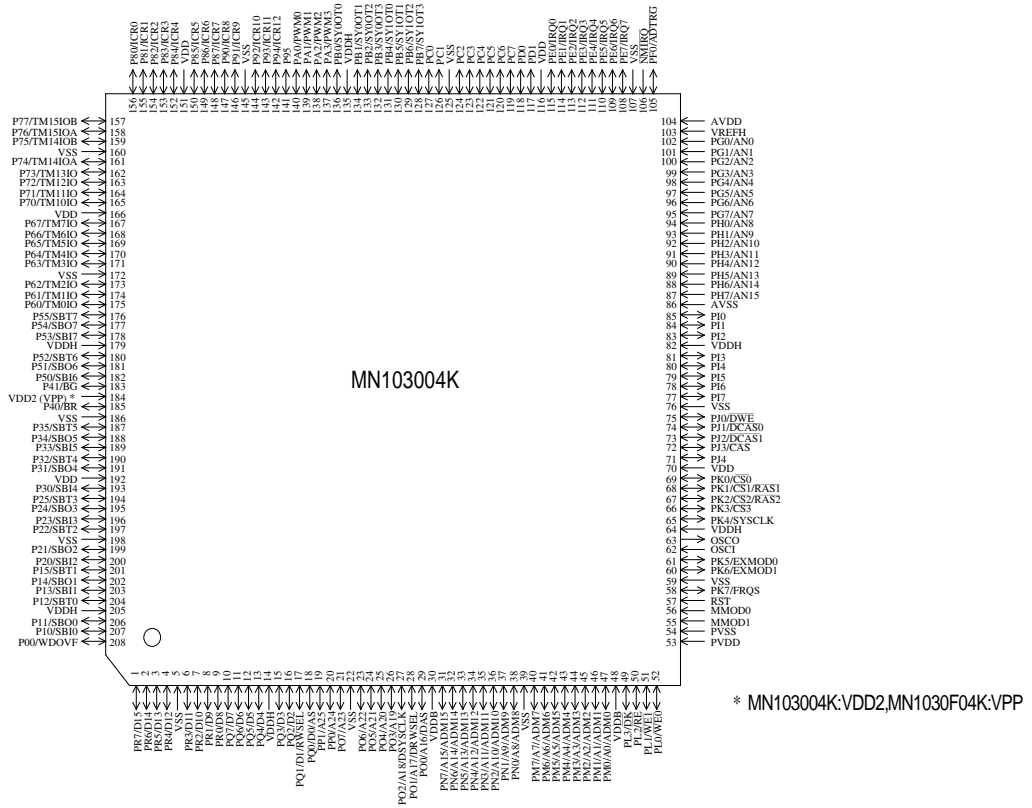
Parameter	Symbol	Condition	Limit			Unit
			min	typ	max	
Resolution					10	Bits
A/D conversion absolute error		VREF+ = 3.0 V A/D conversion clock = 5 MHz			± 7	LSB
A/D conversion relative error					± 5	LSB
A/D conversion time			2.8			μs

(Ta = -20°C to +85°C, AVDD = 3.0 V, AVSS = 0 V)

See the next page for pin assignment and support tool.

Pin Assignment

(): Conventional Package



QFP208-P-2828F *Lead-free

(QFP208-P-2828A)

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